



P-Channel 150-V (D-S) MOSFET

PRODU	CT SUMMARY		
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)
- 150	1.2 at V _{GS} = - 10 V	- 1.3	4.8 nC
- 150	1.3 at V _{GS} = - 6 V	- 1.2	4.6 110

FEATURES

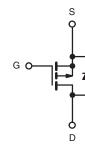
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % UIS Tested

COMPLIANT **HALOGEN**

FREE

APPLICATIONS

- Active Clamp Switch
- Isolated DC/DC Converters



P-Channel MOSFET

	SO-8	
S 1 S 2 S 3 G 4		8 D 7 D 6 D 5 D
	Top View	

Ordering Information: Si4409DY-T1-E3 (Lead (Pb)-free)

Si4409DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 150	V		
Gate-Source Voltage	V _{GS}	± 20	v		
	T _C = 25 °C		- 1.3		
Continuous Prain Current (T. – 150 °C)	T _C = 70 °C		- 1.0		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	- 0.9 ^{b, c}		
	T _A = 70 °C		- 0.7 ^{b, c}	А	
Pulsed Drain Current	I _{DM}	- 2	A		
Continuous Source Drain Diade Current	T _C = 25 °C	I-	- 1.3		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 0.9 ^{b, c}		
Avalanche Current	0.1 m	I _{AS}	4		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	0.8	mJ	
	T _C = 25 °C		4.6		
Maximum Power Dissipation	T _C = 70 °C	ь —	2.9	w	
	T _A = 25 °C	P _D	2.2 ^{b, c}	VV	
	T _A = 70 °C		1.4 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	47	55	°C/W	
Maximum Junction-to-Foot	Steady State	R_{thJF}	22	27]	

Notes:

- a. T_C = 25 °C.
 b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 95 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 150			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 160		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 2		- 4	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Drain Correct		V _{DS} = - 150 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = - 150 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 2			Α	
Durin Course Co Olete Besteley 3	D	V _{GS} = - 10 V, I _D = - 0.5 A		0.95	1.2	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 6 V, I _D = - 0.5 A		1.0	1.3		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 0.5 A		2.2		S	
Dynamic ^b							
Input Capacitance	C _{iss}			332		pF	
Output Capacitance	C _{oss}	$V_{DS} = -50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		25			
Reverse Transfer Capacitance	C _{rss}			13			
T. 10 . 0	Qg	$V_{DS} = -75 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -0.5 \text{ A}$		7.7	7.7 12		
Total Gate Charge				4.8	7.5		
Gate-Source Charge	Q_{gs}	$V_{DS} = -75 \text{ V}, V_{GS} = -6 \text{ V}, I_{D} = -0.5 \text{ A}$		1.5		nC	
Gate-Drain Charge	Q_{gd}			2.5		1	
Gate Resistance	R_{g}	f = 1 MHz		9		Ω	
Turn-On Delay Time	t _{d(on)}			7	14		
Rise Time	t _r	$V_{DD} = -75 \text{ V}, R_{L} = 75 \Omega$		10	20		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_g = 6 Ω		16	30		
Fall Time	t _f	_		9	18	ns	
Turn-On Delay Time	t _{d(on)}			7	14		
Rise Time	t _r	$V_{DD} = -75 \text{ V}, R_{L} = 75 \Omega$		10	20		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1 \text{ A}, V_{GEN} = -6 \text{ V}, R_g = 1 \Omega$		13	25		
Fall Time	t _f	_		10	20		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.3	A	
Pulse Diode Forward Current	I _{SM}				- 2.0		
Body Diode Voltage	V_{SD}	I _S = - 1 A, V _{GS} = 0 V		- 0.7	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			43	70	ns	
Body Diode Reverse Recovery Charge	Q_{rr}	L = 12 A dl/dt = 100 A/vo T = 25 °C		95	150	nC	
Reverse Recovery Fall Time	t _a	$I_F = -1.2 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		40		ns	
Reverse Recovery Rise Time	t _b			3			

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

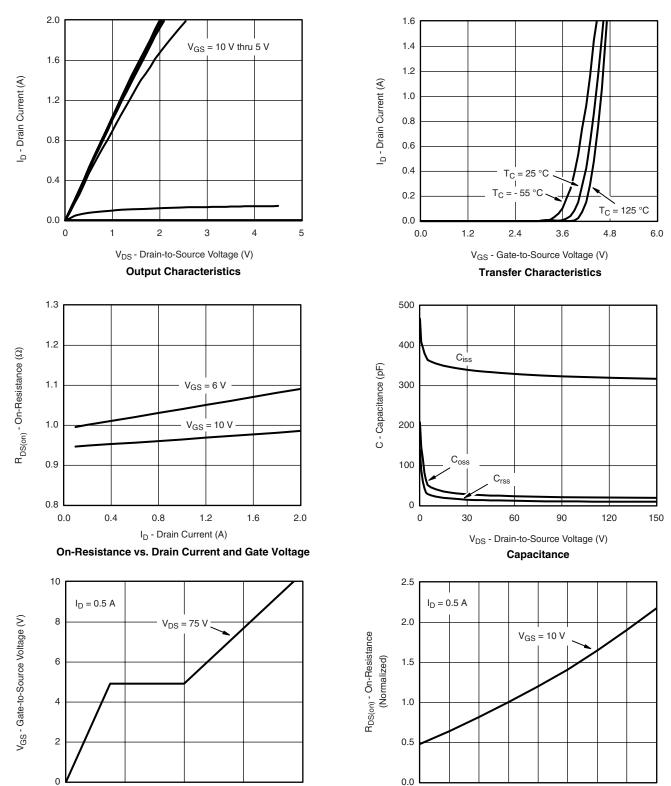
b. Guaranteed by design, not subject to production testing.







TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



- 50

- 25

25

50

T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

75

100

6

0

2

Q_q - Total Gate Charge (nC)

Gate Charge

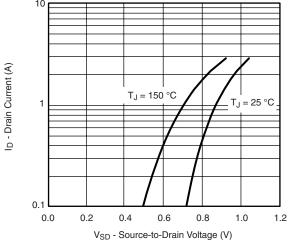
125

150

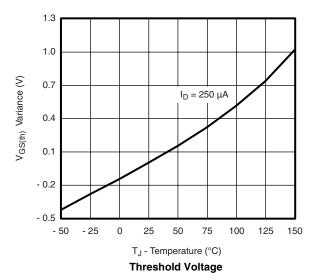
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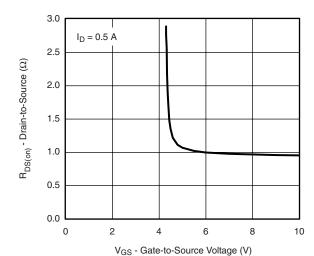
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

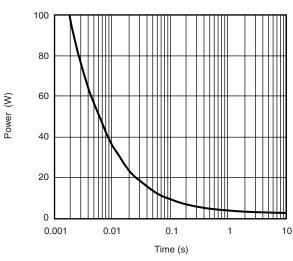


Source-Drain Diode Forward Voltage

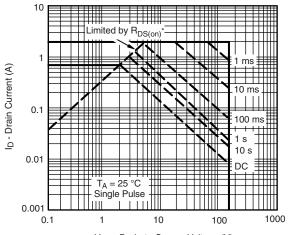




On-Resistance vs. Gate-to-Source Temperature



Single Pulse Power, Junction-to-Ambient

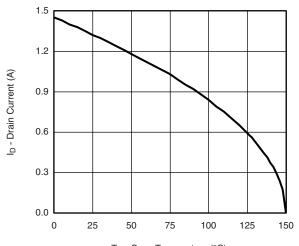


 $\label{eq:VDS} V_{DS} \mbox{ - Drain-to-Source Voltage (V)} \\ \mbox{*} V_{GS} \mbox{ > minimum } V_{GS} \mbox{ at which } R_{DS(on)} \mbox{ is specified}$

Safe Operating Area, Junction-to-Ambient

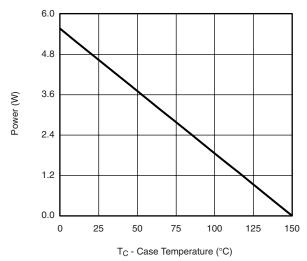


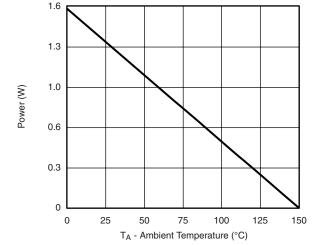
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



T_C - Case Temperature (°C)

Current Derating*





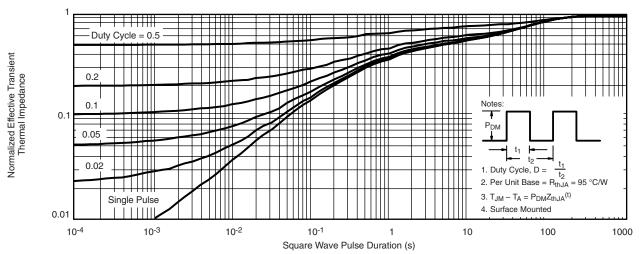
Power, Junction-to-Foot Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

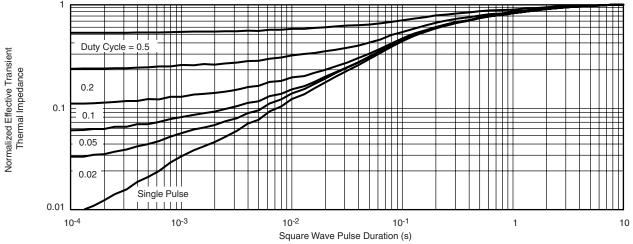
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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